

- STRUCTURE Silicon Monolithic Integrated Circuit
- ♦ PRODUCT I2C BUS 128Kbit (16,384 × 8bit) EEPROM
- ♦ PART NUMBER BU9897GUL-W

PART NUMBER	PACKAGE
BU9897GUL-W	VCSP50L2

♦ FEATURES Two wire serial interface Wide operating voltage range (1.7V~5.5V) Endurance : 1,000,000 erase/write cycles

#### ♦ ABSOLUTE MAXIMUM RATING (Ta=25°C)

Parameter	Symbol	Rating		Unit
Supply Voltage	Vcc	-0.3~6.5		V
Power Dissipation	Pd	220	*1	mW
Storage Temperature	Tstg	-65~125		°C
Operating Temperature	Topr	-40~85		°C
Terminal Voltage	—	-0.3~Vcc+1.0	*2	V

\*1 2.2mW/°C(\*1) for operation above  $25^{\circ}C$ 

\*2 The Max value of Terminal Voltage is not over 6.5V

#### ♦ RECOMMENDED OPERATING CONDITION

Parameter	Symbol	Rating	Unit
Supply Voltage	Vcc	1.7~5.5	V
Input Voltage	VIN	0~Vcc	V



#### ♦ MEMORY CELL CHARACTERISTICS (Ta=25°C, Vcc=1.7~5.5V)

Parameter			Unit		
Parameter		Min.	Тур.	Max.	Unic
Write/Erase Cycle	*1	1,000,000	-	-	Cycles
Data Retention	*1	40	-	-	Years

OInitial Data FFh in all address.

#### ♦ DC OPERATING CHARACTERISTICS

**♦BLOCK DIAGRAM** 

\$ 20 01 E10							
Parameter	Symbol	Specification			Unit	Specification	
		Min.	Min.	Min.		•	
"H" Input Voltage1	VIH1	0.7Vcc		Vcc+1.0	V		
"L" Input Voltage1	VIH2	-0.3	-	0.3Vcc	V		
"L" Output Voltage1	VOL1	-	-	0.4	V	IOL=3.0mA, 2.5V≦Vcc≦ 5.5V (SDA)	
"L" Output Voltage2	VOL2	-	-	0.2	V	IOL=0.7mA, 1.7V≦Vcc< 2.5V (SDA)	
Input Leakage Current	ILI	-1	-	1	μA	VIN=0V~Vcc	
Output Leakage Current	ILO	-1	-	1	μA	VOUT=0V~Vcc (SDA)	
Operating Current	ICC1	_	-	2.5	mA	Vcc=5.5V,fSCL=400 k Hz, tWR=5ms Byte Write,Page Write	
Operating Cullent	ICC2	_	_	0.5	mA	Vcc=5.5V,fSCL=400 k Hz Random Read,Current Read,Sequential Read	
Standby Current	ISB	_	—	2.0	μA	Vcc=5.5V,SDA,SCL=Vcc A0,A1,A2=GND,WP=GND	

\*1 Not 100% TESTED

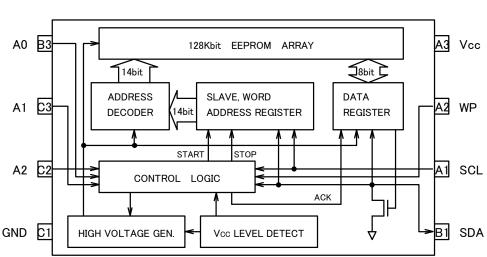
#### (Unless otherwise specified Ta=-40~85°C, Vcc=1.7~5.5V)

♦ AC OPERATING CHARACTERISTICS

(0111000 0	ittlerwise spe		pecification		0.017
Parameter	Symbol	Min.	Typ.	Max.	Unit
Clock Frequency	fSCL	-	-	400	kHz
Data Clock High Period	tHIGH	0.6	-	-	μs
Data Clock Low Period	tLOW	1.2	-		Ms
SDA and SCL Rise Time *1	tR			0.3	Ms
SDA and SCL Fall Time *1	tF	-	-	0.3	Ms
Start Condition Hold Time	tHD:STA	0.6	-	-	Ms
Start Condition Setup Time	tSU:STA	0.6	-	-	μs
Input Data Hold Time	tHD:DAT	0	-	-	ns
Input Data Setup Time	tSU:DAT	100	-	-	ns
Output Data Delay Time	tPD	0.1	-	0.9	μs
Output Data Hold Time	tDH	0.1			μs
Stop Condition Setup Time	tSU:STO	0.6	-		μs
Bus Free Time	tBUF	1.2	-		μs
Write Cycle Time	tWR	-	-	5	ns
Noise Spike Width (SDA and SCL)	tl	_	_	0.1	μs
WP Hold Time	tHD:WP	0	-	-	ns
WP Setup Time	tSU:WP	0.1	-	-	μs
WP High Period	tHIGH:WP	1.0	-	-	μs

\*1 Not 100% TESTED

## ♦ PIN No. NAME



	PIN No.	PIN NAME
	A1	SCL
>	A2	WP
	A3	Vcc
	A4	GND
	B1	SDA
	B3	A0
	B4	GND
	C1	GND
L	C2	A2
	C3	A1
	C4	GND

Fig.-1 BLOCK DIAGRAM



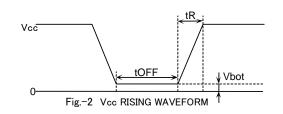
### ♦NOTES FOR POWER SUPPLY

Vcc rises through the low voltage region in which internal circuit of IC and the controller are unstable, so that device may not work properly due to an incomplete reset of internal circuit. To prevent this, the device has the feature of P.O.R. and LVCC. In the case of power up, keep the following conditions to ensure functions of P.O.R. and LVCC.

SCI

SDA \_\_\_\_\_ After Vcc becomes stable

- 1. It is necessary to be "SDA='H'" and "SCL='L' or 'H'".
- 2. Follow the recommended conditions of tR, tOFF, Vbot for the function of P.O.R. during power up.



♦ RECOMMENDED CONDITIONS OF tR, tOFF, Vbot

Vcc becomes stable

+SU DAT

Fig.-3(b) SCL='L' and SDA='L'

tLOW

tDH 'tSU:DAT

Fig.-3(a) SCL='H' and SDA='L'

3. Prevent SDA and SCL from being "High-Z".

In case that condition 1. and/or 2. cannot be met, take following actions.

A) Unable to keep condition 1.

(SDA is "LOW" during power up.)

 $\rightarrow$ Control SDA ,SCL to be "HIGH" as Fig.-3(a),

3(b).

B)Unable to keep condition 2.

→After power becomes stable, execute

C)Unable to keep both conditions 1 and 2.

 $\rightarrow$ Follow the instruction A first, then the instruction B.

### ♦ CAUTIONS ON USE

(1) Absolute maximum ratings

If the absolute maximum ratings such as impressed voltage and action temperature range and so forth are exceeded, LSI may be destructed. Do not impress voltage and temperature exceeding the absolute maximum ratings. In the case of fear exceeding the absolute maximum ratings, take physical safety countermeasures such as fuses, and see to it that conditions exceeding the absolute maximum ratings should not be impressed to LSI.

(2) GND electric potential

Set the voltage of GND terminal lowest at any action condition. Make sure that each terminal voltage is not lower than that of GND terminal.

(3) Thermal design

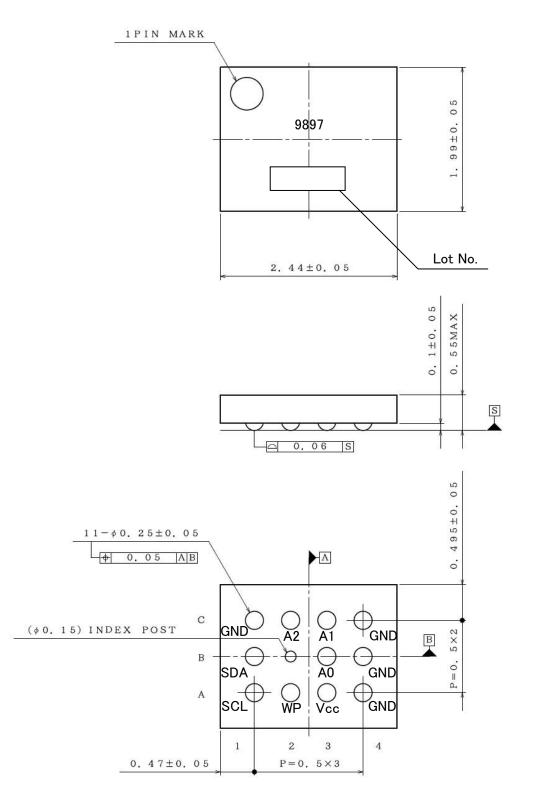
In consideration of permissible loss in actual use condition, carry out heat design with sufficient margin.

(4) Terminal to terminal shortcircuit and wrong packaging

When to package LSI onto a board, pay sufficient attention to LSI direction and displacement. Wrong packaging may destruct LSI. And in the case of shortcircuit between LSI terminals and terminals and power source, terminal and GND owing to foreign matter, LSI may be destructed.

(5) Use in a strong electromagnetic field may cause malfunction, therefore, evaluated design sufficiently.





The A4, B4, C4 pins are set to GND inside chip. Please set these OPEN. Please don't connect these GND.

(UNIT:mm)

Drawing No:EX912-5052

Fig.-1 PHYSICAL DIMENSION (UNIT:mm)

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